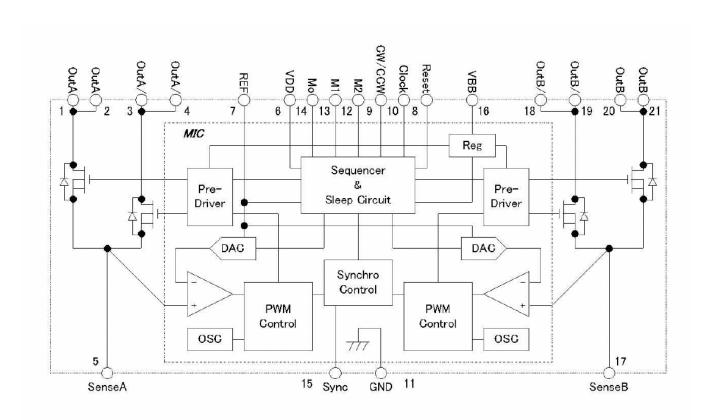
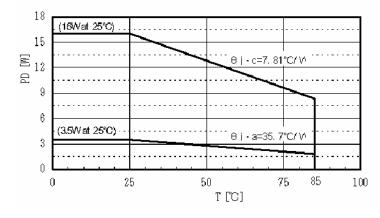


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Recommended operating conditions

Loa	ad Supply Voltage, V _{BB}	10 to 44 V
Log	gic Supply Voltage, V _{DD}	3.0 V to 5.5 V
Re	ference Input Voltage, V _{REF}	0.1 V to 1.0 V
Tal	b Temperature (no heat sink), T⊤	<90°C



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Electrical characteristics: unless otherwise noted at $T_A = +25$ °C, $V_{BB} = 24$ V, $V_{DD} = 5.0$ V.

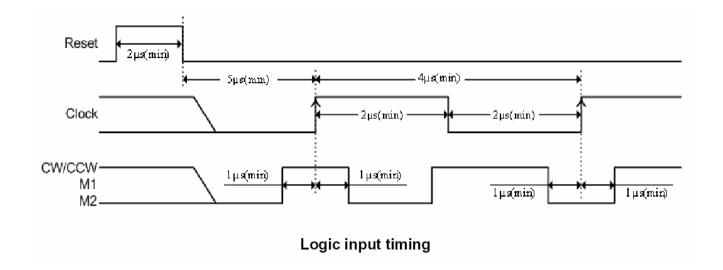
		7		Limits			
Characteristic	Symbol	Test Conditions	Min.	Тур.	Max.	Units	
Output drivers							
Driver Supply Volt. Range	V _{BB}	Operating	10	_	44	V	
Drain-Source Breakdown	V _{(BR)DS}	V _{BB} = 44 V, I _D = 1 mA	100	_	_	V	
Output On Resistance	r _{DS(on)}	SLA7060M, I _O = 1.0 A	_	700	850	mΩ	
		SLA7061M, I _O = 2.0 A	_	250	400	mΩ	
		SLA7062M, I _O = 3.0 A	_	180	240	mΩ	
Body Diode Forward Volt.	V _F	SLA7060M, I _F = 1.0 A	_	0.85	1.1	V	
		SLA7061M, I _F = 2.0 A	_	0.95	1.2	V	
		SLA7062M, I _F = 3.0 A	_	0.95	2.1	V	
Driver Supply Current	I _{BB}		_	_	15	mA	
		V _{REF} > 2.0 V (sleep mode)	_	_	100	μΑ	
Control logic		•	•				
Logic Supply Volt. Range	V_{DD}	Operating	3.0	5.0	5.5	V	
Logic Input Voltage	V _{IH}		0.75V _{DD}	_	_	V	
	V _{IL}		_	_	0.25V _{DD}	V	
Logic Input Current	I _{IH}		_	±1.0	_	μΑ	
	I _{IL}	CLOCK, RESET, CW/CCW, and SYNC.	_	±1.0	_	μΑ	
		M1 and M2	-25	-50	-75	μΑ	
Max. Clock Frequency	f _{clk}		250*	_	_	kHz	
PWM Off Time	t _{off}	70 to 100%I _{trip} max	_	12	_	μs	
		38 to 64%I _{trip} max	_	9.0	_	μs	
		9 to 30%l _{trip} max	_	7.0	_	μs	
PWM Min. On Time	t _{on(min)}		_	1.8	_	μs	
Ref. Input Voltage Range	V _{REF}	Operating	0	_	1.5	V	
		Sleep mode	2.0	_	V_{DD}	V	
Ref. Input Current	I _{REF}		_	±10	_	μΑ	
Monitor Output Voltage	V _{MoH}		V _{DD} - 1.25	_	_	V	
	V _{MoL}		_	_	1.25	V	
Monitor Output Current	I _{Mo}		_	_	±3.0	mA	
Sense Voltage	V _s	Trip point at 100% I _O	0.95V _{REF}	V_{REF}	1.05V _{REF}	V	
Sense Input Current	I _{SENSE}			±10	_	μΑ	
Propagation Delay Time	t _{PLH}	Clock rising edge to output on	_	2.0		μs	
	t _{PHL}	Clock rising edge to output off	_	1.5		μs	
Logic Supply Current	I _{DD}		_	_	4.0	mA	

Typical values are given for circuit design information only.

*Operation at a clock frequency greater than the specified minimum value is possible but not warranted.

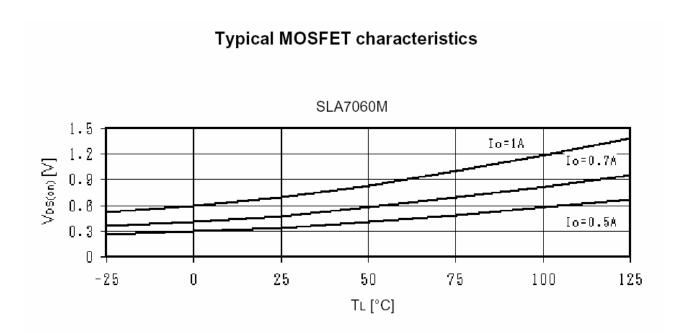


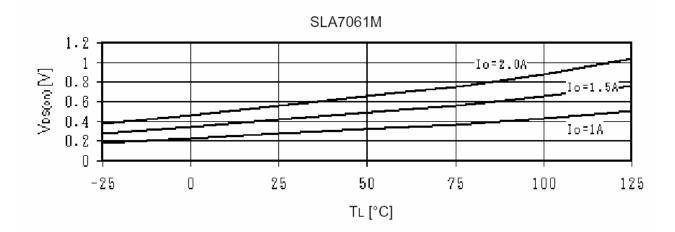
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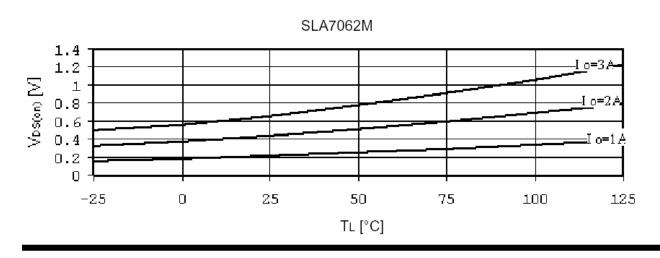




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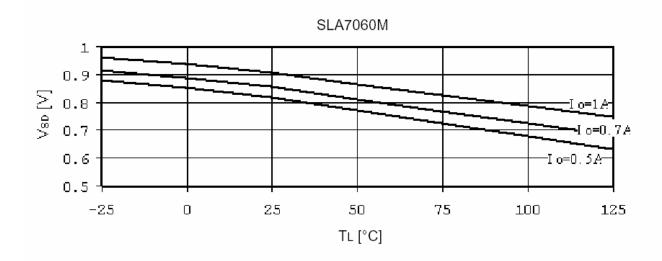


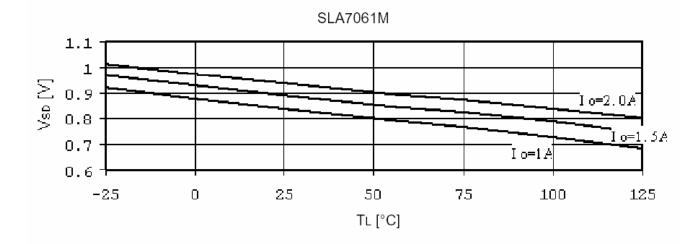


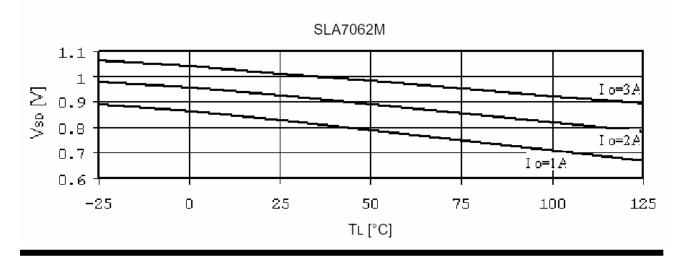


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Typical body diode characteristics









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Functional description

Device operation. These devices are complete microstepping motor drivers with built in translator for easy operation with minimal control lines. They are designed to operate unipolar stepper motors in half-, quarter-, eighth-, and sixteenth-step modes. The current in each of the four outputs, all n-channel DMOS, is regulated with fixed off time pulse-width modulated (PWM) control circuitry. The current at each step is set by the value of an external current-sense resistor ($R_{\rm S}$), a reference voltage ($V_{\rm REF}$), and the DAC's output voltage controlled by the output of the translator.

At V_{DD} power up, or reset, the translator sets the DACs to the home state (see figures for reset conditions). When a step command signal occurs on the CLOCK input the translator automatically sequences the DACs to the next level (see table 2 for the current level sequence). The microstep resolution is set by inputs M1 and M2 as shown in table 1.

RESET input. The RESET input sets the translator to a predefined home state (see table 2); this is not the same as the sleep mode. The monitor output (MO) goes low and all STEP inputs are ignored until the RESET input goes low. A low-pass filter is integrated into the reset circuit; therefore a 5 μs delay is required between the falling edge of the RESET input and the rising edge of the CLOCK input.

Monitor output (MO). A logic output indicator of the initial/home state of the translator (45°). At power up the translator is reset to the home state (phase A and phase B output currents are both at the half-step position or 70.7%). This output is also high at the 135°, 225°, and 315° positions.

CLOCK (step) input. A low-to-high transition on the clock input sequences the translator, which controls the input to the DACs and advances the motor one increment. The size of the increment is determined by the state of inputs M1 and M2 (see table 1). The hold state is done by stopping the CLOCK input regardless of the input level.

Microstep select (M1 and M2). These logic-level inputs set the translator step mode per table 1. Changes to these inputs do not take effect until the rising edge of the clock input.

Direction (CW/CCW) input. This logic-level input sets the translator step direction. Changes to this input do not take effect until the rising edge of the clock input.

Internal PWM current control. Each pair of outputs is controlled by a fixed off-time (7 to 12 μ s, depending on step) PWM current-control circuit that limits the load current to a desired value (I_{TRIP}). Initially, an output is enabled and current flows through the motor winding and R_S . When the voltage across the current-sense resistor equals the DAC output voltage, the current-sense comparator resets the PWM latch, which turns off the driver for the fixed off time during which the load inductance causes the current to recirculate for the off time period. The driver is then re-enabled and the cycle repeats.

Synchronous operation mode. This function prevents occasional motor noise during a "hold" state, which normally results from asynchronous PWM operation of both motor phases. A logic high at the SYNC input is synchronous operation; a logic low is asynchronous operation. The use of synchronous operation during normal stepping is not recommended because it produces less motor torque and can cause motor vibration due to staircase current.

Sleep mode. Applying a voltage greater than 2 V to the REF pin disables the outputs and puts the motor in a free state (coast). This function is used to minimize power consumption when not in use. Although it disables much of the internal circuitry including the output MOSFETs and regulator, the sequencer/translator circuit is active and therefore a microcontroller can set the step starting point for the next operation during the sleep mode. When coming out of sleep mode, wait 100 μs before issuing a step command to allow the internal circuitry to stabilize.

Table 1. Step Modes

Input M1	Input M2	Step Mode	
Н	Н	Half Step	
Н	L	Quarter Step	
L	Н	Eighth Step	
L	L	Sixteenth Step	



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Table 2. Step Sequencing

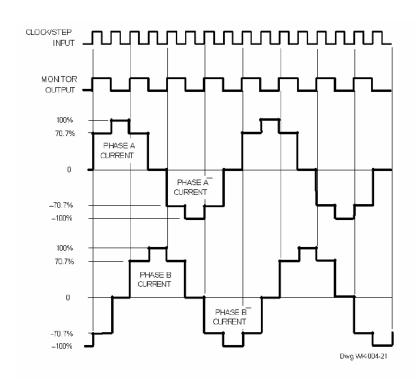
			(CW/CCW =	Phase A or A\	Phase B or B\	
Half	Quarter	Eighth	Sixteenth	Current	Current	Step
Step#	Step #	Step #	Step #	[%l _{trip} max]	[%I _{trip} max]	Angle
0	0	0	0	70.7	70.7	45*
			1	77.3	63.4	
		1	2	83.1	55.5	
			3	88.2	47.1	
	1	2	4	92.4	38.2	67.5
			5	95.7	29.0	
		3	6	98.1	19.5	
1	2	4	7 8	100 100	9.8 0	90
'	2	4	9	100	-9.8	90
		5	10	98.1	-19.5	
		J	11	95.7	-29.0	
	3	6	12	92.4	-38.2	102.5
			13	88.2	-47.1	
		7	14	83.1	-55.5	
			15	77.3	-63.4	
2	4	8	16	70.7	-70.7	135†
_		-	17	63.4	-77.3	
		9	18	55.5	-83.1	
			19	47.1	-88.2	
	5	10	20	38.2	-92.4	157.5
			21	29.0	-95.7	
		11	22	19.5	-98.1	
		4.0	23	9.8	-100	400
3	6	12	24	0	-100	180
		40	25	-9.8	-100	
		13	26	-19.5	-98.1	
	7	14	27 28	-29.0 -38.2	-95.7 -92.4	202.5
	ľ	14	29	-36.2 -47.1	-88.2	202.5
		15	30	-55.5	-83.1	
		10	31	-63.4	-77.3	
4	8	16	32	-70.7	-70.7	225†
4	0	16	33	-77.3	-63.4	223
		17	34	-83.1	-55.5	
			35	-88.2	-47.1	
	9	18	36	-92.4	-38.2	247.5
			37	-95.7	-29.0	
		19	38	-98.1	-19.5	
			39	-100	-9.8	
5	10	20	40	-100	0	270
			41	-100	9.8	
		21	42	-98.1	19.5	
	4.		43	-95.7	29.0	
	11	22	44	-92.4	38.2	292.5
		22	45 46	-88.2	47.1	
		23	46 47	-83.1 -77.3	55.5 63.4	
6	12	24	48	-70.7	70.7	2484
б	12	24	48 49	-70.7 -63.4	70.7 77.3	315†
		25	50	-63.4 -55.5	83.1	
		23	51	-35.5 -47.1	88.2	
	13	26	52	-38.2	92.4	337.5
	10	20	53	-29.0	95.7	0.7.0
		27	54	-19.5	98.1	
			55	-9.8	100	
7	14	28	56	0	100	360
			57	9.8	100	
		29	58	19.5	98.1	
			59	29.0	95.7	
	15	30	60	38.2	92.4	22.5
			61	47.1	88.2	
		31	62	55.5	83.1	
			63	63.4	77.3	
8	16	32	64	70.7	70.7	45*

^{*} Home state: MO output high.

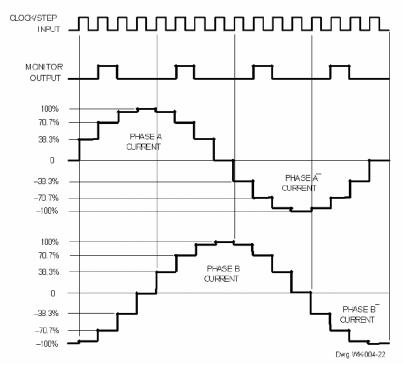
⁺ MO output high



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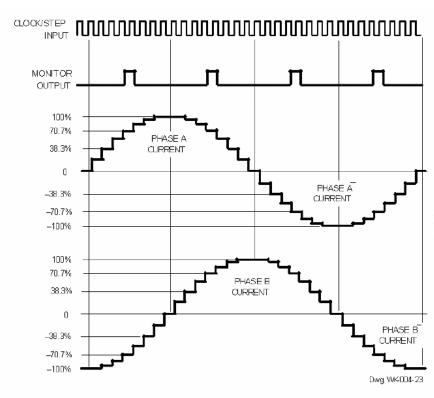
Half-step output current waveshapes. For illustrative purposes, phase A\ or B\ current (unipolar drive) is shown as negative current.



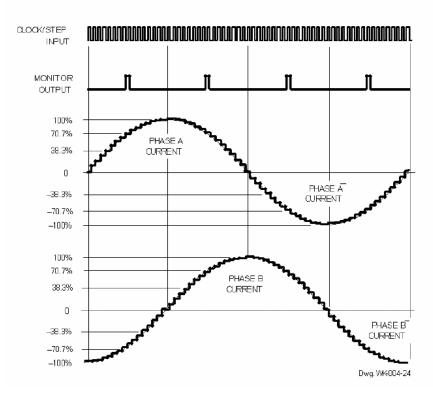
Quarter-step output current waveshapes. For illustrative purposes, phase A\ or B\ current (unipolar drive) is shown as negative current.



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Eighth-step output current waveshapes. For illustrative purposes, phase A\ or B\ current (unipolar drive) is shown as negative current.



Sixteenth-step output current waveshapes. For illustrative purposes, phase A\ or B\ current (unipolar drive) is shown as negative current.



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Applications information

Layout.

The printed wirting board should use a heavy ground plane.

For optimum electrical and thermal performance, the driver should be soldered directly into the board.

The driver supply terminal, VBB, should be decoupled with an electrolytic capacitor (>47 μ F is recommended) placed as close to the device as possible.

To avoid problems due to capacitive coupling of the high dv/dt switching transients, route the high-level, output traces away from the sensitive, low-level logic traces. Always drive the logic inputs with a low source impedance to increase noise immunity.

Grounding. A star ground system located close to the driver is recommended. The logic supply return and the driver supply return should be connected together at only a single point — the star ground.

Logic supply voltage, V_{DD}. Transients at this terminal should be held to less than 0.5 V to avoid malfunctioning operation. Both V_{BB} and V_{DD} may be turned on or off separately.

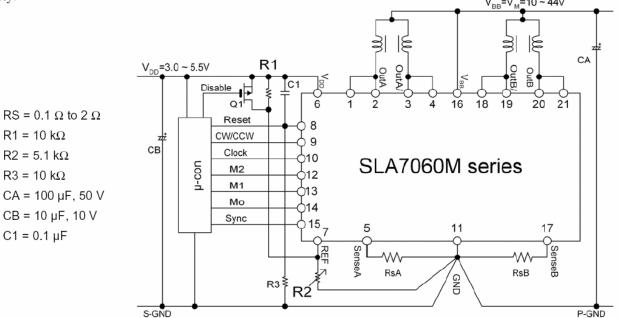
Logic inputs. Unused logic inputs (CW/CCW, M1, M2, RESET, or SYNC) must be connected to either ground or the logic supply voltage.

Current sensing. To minimize inaccuracies caused by ground-trace IR drops in sensing the output current level, the current-sense resistors, $R_{\rm S}$, should have an independent ground return to the star ground of the device. This path should be as short as possible. For low-value sense resistors, the IR drops in the printed wiring board sense resistor's traces can be significant and should be taken into account. The use of sockets should be avoided as they can introduce variation in $R_{\rm S}$ due to their contact resistance.

PWM current control. The maximum value of current limiting (I_{TRIP}) is set by the selection of R_S and the voltage at the REF input with a transconductance function approximated by:

$$I_{TRIP} = V_{REF}/R_S$$

The required $V_{\rm REF}$ should not be less than 0.1 V. If it is, $R_{\rm S}$ should be increased for a proportionate increase in $V_{\rm REF}$.





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Applications Information (cont'd)

Reference voltage. In the Typical Application shown, resistors R_1 and R_2 set the reference voltage as:

$$V_{REF} = (V_{DD} \times R_2)/(R_1 + R_2)$$

The trimming of R_2 allows for the resistor tolerances and REF input current. The sum of $R_1 \! + \! R_2$ should be less than $50~k\Omega$ to minimize the effect of I_{REF} . Raising V_{REF} above 2~V by activating Q1 causes the sleep mode.

Minimum output current. The Series SLA7060M uses fixed off-time PWM current control. Due to internal logic and switching delays, the actual load current peak will be slightly higher than the calculated I_{TRIP} value (especially for low-inductance loads). These delays, plus the minimum recommended V_{REF} , limit the minimum value the current-control circuitry can regulate. An application with this device should maintain continuous PWM control in order to obtain optimum torque out of the motor. The boundary of the load current ($I_{O(min)}$) between continuous and discontinuous operation is:

$$I_{O(min)} = [(V_M + V_{SD})/R_m] \times [(1/e^{toff/[R_m \times L_m]}) - 1]$$

where $V_{M} = load$ supply voltage

 V_F = body diode forward voltage

 $R_{m} = motor winding resistance$

 $t_{off} = PWM \text{ off time}$

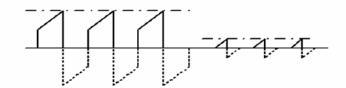
 $\overline{L_m}$ = motor winding inductance

To produce zero current in a motor, the REF input should be pulled above 2 V, turning off all drivers.

Synchronous operation mode. If an external signal is not available to control the synchronous operation mode, a simple circuit can keep the SYNC input low while the CLOCK input is active; the SYNC input will go high (synchronous operation) when the CLOCK input stays low ("hold"). The RC time constant determines the sync transition timing.

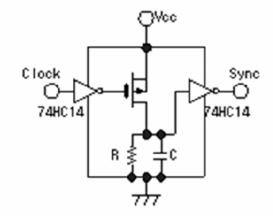
NOTE –The use of this function except at 0, 70.7, or 100% l_{trip}max (half-step positions 0 through 8) is not recommended.

Temperature effects on FET outputs. Analyzing safe, reliable operation includes a concern for the relationship of NMOS on resistance to junction temperature. Device package power calculations must include the increase in on resistance (producing higher on voltages)

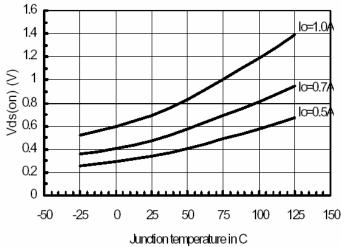


Continuous mode

Discontinuous mode



Sync. signal generator



Normalized FET on resistance



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Applications Information (cont'd)

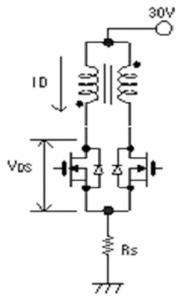
caused by increased operating junction temperatures. The figure provides a normalized on-resistance curve, and all thermal calculations should consider increases from the given +25°C limits, which may be caused by internal heating during normal operation.

These power MOSFET outputs feature an excellent combination of fast switching, ruggedized device design, low on resistance, and cost effectiveness.

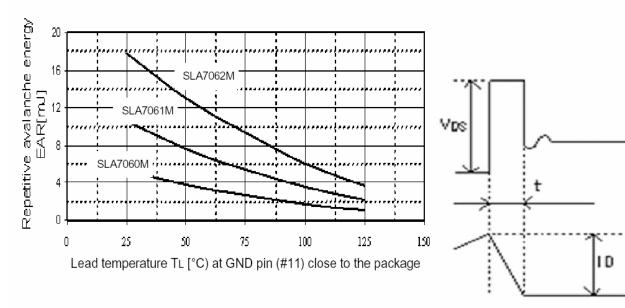
Avalanche energy capability. There is a surge voltage expected when the output MOSFET turns off, and this voltage may exceed the MOSFET breakdown voltage $(V_{(BR)DS})$. However, the MOSFETs are avalanche type and as long as the energy $(E_{(AV)})$, which is imposed on the MOSFET by the surge voltage, is less than the maximum allowable value, it is considered to be within its safe operating area. Note that the maximum allowable avalanche energy is reduced as a function of temperature.

In application, the avalanche energy $(E_{(AV)})$ dissipated by the MOSFET is approximated as

$$E_{(AV)} = V_{DS(AV)} \times 0.5 \times I_D \times t$$



Output circuit for avalanche energy calculations



Allowable avalanche energy

Waveforms during avalanche breakdown



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Terminal list

Pin	Terminal Name	Terminal Description
1, 2	OUTA	Driver outputs for phase A
3, 4	OUTA\	Driver outputs for phase A\
5	SENSEA	Phase A current sense
6	VDD	Logic power supply, $V_{\rm DD}$
7	REF	Current set & "sleep" control
8	RESET	Logic control input
9	CW/CCW	Forward/reverse logic control input
10	CLOCK	Step clock input
11	GND	Supply negative return
12	M2	Step mode logic control input
13	M1	Step mode logic control input
14	MO	Monitor logic output
15	SYNC	Synchronous PWM control input
16	VBB	Driver power supply, $V_{\rm BB}$
17	SENSEB	Phase B current sense
18, 19	OUTB\	Driver outputs for phase B\
20, 21	OUTB	Driver outputs for phase B

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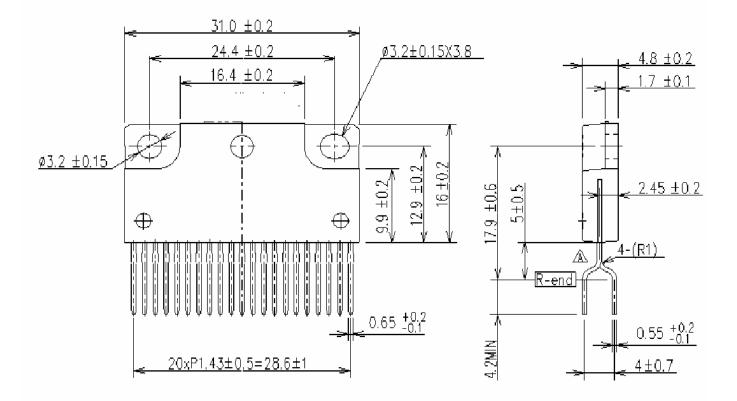
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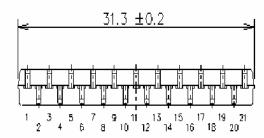
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SLA706xMLF2102 Dimensions in millimeters

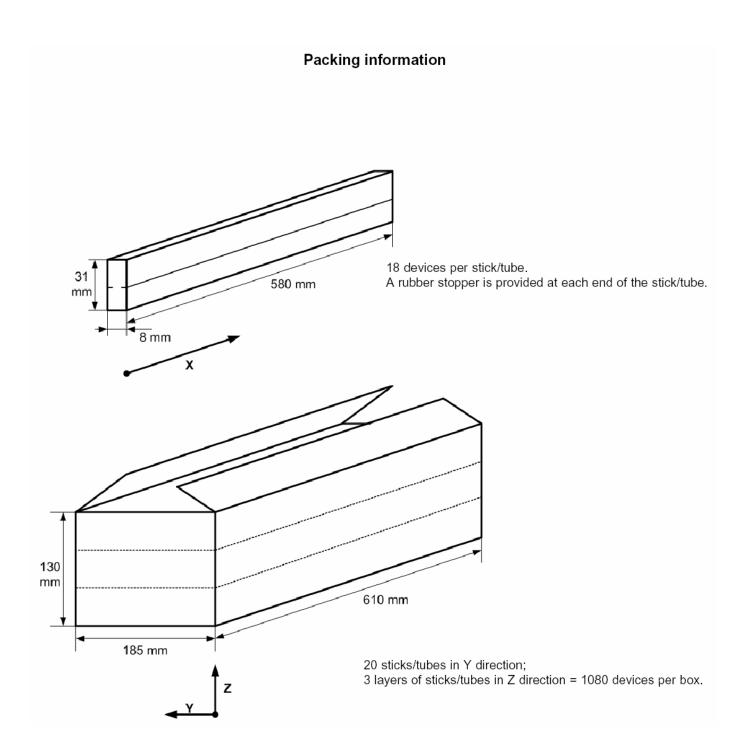




- NOTES: 1. Exact body and lead configuration at vendor's option within limits shown.
 - 2. Lead spacing tolerance is non-cumulative.
 - 3. Recommended mounting hardware torque: 0.490 0.822 Nm.
 - 4. Recommended use of metal-oxide-filled, alkyl-degenerated oil-base silicone grease: Dow Corning SC102, Toshiba YG6260, Shin-Etsu G746, or equivalent.



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